

Multilayer Power Inductor

CIG21W Series (2012/ EIA 0805)



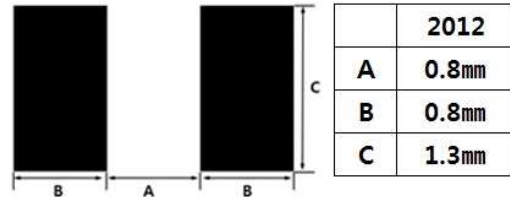
APPLICATION

Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

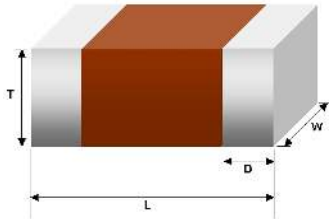
FEATURES

- Low Profile (1.0mm max)
- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability

RECOMMENDED LAND PATTERN



DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
21	2.0±0.2	1.25±0.2	0.9±0.1	0.5+0.2 -0.3

DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) Max.
CIG21W1R0MNE	0805/2012	1.0 ±25 %	0.133 ±20 %	1.05
CIG21W1R5MNE	0805/2012	1.5 ±25 %	0.150 ±20 %	0.96
CIG21W2R2MNE	0805/2012	2.2 ±20 %	0.200 ±20 %	0.81
CIG21W3R3MNE	0805/2012	3.3 ±20 %	0.250 ±20 %	0.73
CIG21W4R7MNE	0805/2012	4.7 ±20 %	0.300 ±20 %	0.65

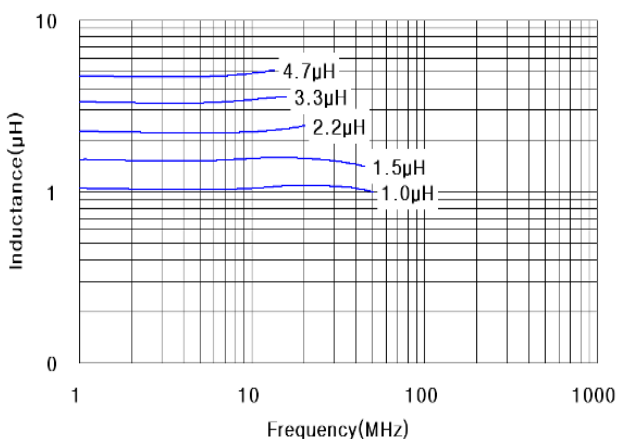
※Rated Current: DC current value when the self-generation of heat rises to 40℃ (Reference ambient temperature:25℃)

※Operating temperature range: -40 to +125℃ (Including self-temperature rise)

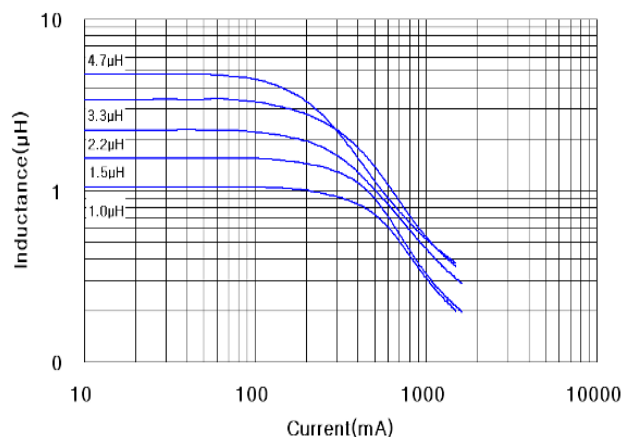
※Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



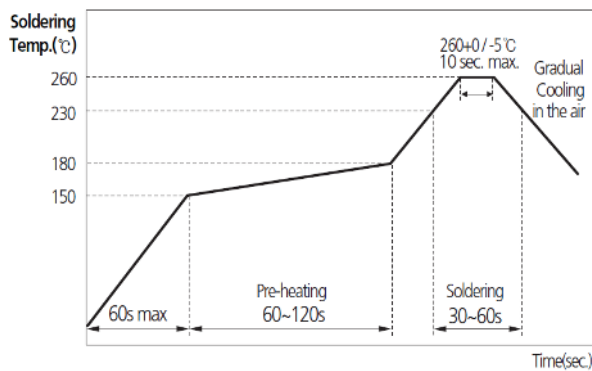
PRODUCT IDENTIFICATION

CI G 21 W 1R0 M N E
(1) (2) (3) (4) (5) (6) (7) (8)

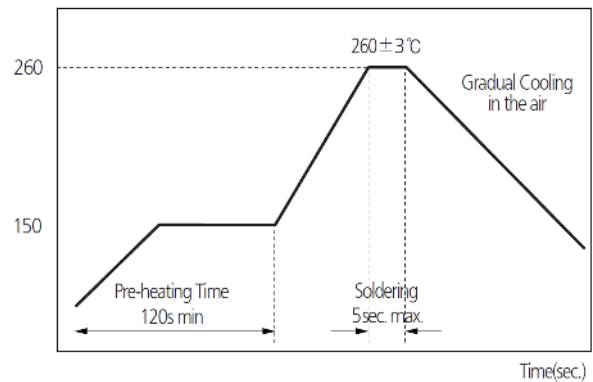
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (W:Normal Type)
- (5) Inductance (1R0:1.0uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING




FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	3,000

 Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.